

**AMENDMENTS TO THE CLAIMS**

A complete list of all the presently pending claims in the application is provided below, with suitable headings to show the status of each claim.

1. (Currently amended) A separating device for separating edge portions from a glass panel, said glass panel having a width and thickness, said device comprising a handle, a force gauge attached to said handle for measuring the force applied to said handle, and a slotted plate connected to said handle, said slotted plate having upper and lower panel engaging surfaces defining a recess of approximately the same width and thickness as said glass panel to be separated, ~~wherein the force applied to said handle is applied in a downward direction.~~

2. (Canceled)

3. (Original) The separating device of claim 1 wherein said slotted plate is comprised of an electrostatic dissipative material disposed to contact said glass panel.

4. (Original) The separating device of claim 3 wherein said electrostatic dissipative material is a polyacetal plastic alloy.

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Withdrawn) A method for separating edge portions of a glass panel etched with semiconductor circuitry, said method comprising:

scoring said glass panel to outline at least one edge portion of said glass panel to be removed;

applying a force evenly along a substantial portion of said at least one edge portion to be removed;

measuring said force with a force gauge; and

controlling an amount of force applied to said glass panel to use a minimal amount of force necessary to separate said at least one edge portion.

9. (Withdrawn) The method of separating glass panels of claim 8 wherein said force is applied manually using a separation handle.

10. (Withdrawn) The method of claim 8, further comprising:

placing said glass panel upon a top surface of a separating apparatus; and

locating said glass panel upon said separating apparatus at a predetermined position with respect to a reference point, in order to locate a scoring line on the flat panel at a desired position relative to the separating apparatus.

11. (Withdrawn) The method of separating a glass panel of claim 8 further comprising:

applying a similar force to the remaining edge portions to be removed without relocating said glass panel on said separating apparatus.

12. (Withdrawn) The method of separating a glass panel of claim 8 wherein said top surface of said separating apparatus is made of an electrostatic dissipative material.

13. (Withdrawn) The method of separating a glass panel of claim 81 wherein said glass panel is located by utilizing multiple locating pins to position said glass panel on said separating apparatus.

14. (Withdrawn) The method of separating a glass panel of claim 11 wherein said glass panel floats above said separating apparatus while said glass panel is being located.

15. (Withdrawn). The method of separating a glass panel of claim 12 wherein said separating apparatus provides a vacuum to hold said glass panel tightly against said separating apparatus once said glass panel is located on said separating apparatus.

16. (Withdrawn) A method of separating edge portions of a glass panel etched with semiconductor circuits, said method comprising:

scoring said glass panel to outline at least one edge portion of said glass panel to be removed;

applying a force evenly along a substantial portion of said at least one edge portion to be removed;

placing said glass panel proximate the top surface of a separating apparatus;

pumping gas under said glass panel so that said glass panel floats above said separating apparatus;

locating said glass panel using locating pins;

providing a vacuum to hold said glass panel tightly against said separating apparatus;

applying a force to the edge of said glass panel until said edge is removed;

measuring said force with a force gauge;

controlling an amount of force applied to said glass panel to use a minimal amount of force necessary to separate said at least one edge portion;

applying a similar force to the remaining edge portions to be removed without relocating said glass panel on said separating apparatus.

17. (Previously presented) The separating device of claim 1, wherein the force applied to said handle is applied in a ~~non-twisting~~ linear manner.

18. (Previously presented) A system configured to facilitate separating edge portions from a glass panel etched with semiconductor circuitry, the glass panel being scored to define an inner working area and outer edge portions to be removed, the system comprising:

a stage having a plurality of channels formed therethrough and a layer of electrostatic dissipative material that covers an upper surface of said stage, wherein gas is pumped through said channels along the underside of the glass panel such that the glass panel floats above said layer of electrostatic dissipative material; and

locating pins that are removably secured to said stage, wherein said locating pins locate the glass panel above said stage, the gas no longer being pumped through said channels after the glass panel is located above said stage so that the glass panel directly contacts said layer of electrostatic dissipative material, and wherein at least one of the outer edge portions is located outside a periphery of said stage when the glass panel directly contacts said layer of electrostatic dissipative material.

19. (Previously presented) The system of claim 18, further comprising a turntable supporting said stage, said turntable configured to mechanically rotate said stage.

20. (Previously presented) The system of claim 18, wherein the gas is nitrogen.

21. (Previously presented) The system of claim 18, further comprising a separating device for separating the outer edge portions from the glass panel, said separating device comprising a handle and a slotted plate connected to said handle, said slotted plate having upper and lower panel engaging surfaces defining a recess of approximately the same width and thickness as the glass panel.

22. (Previously presented) The system of claim 21, wherein said separating device further comprises a force gauge attached to said handle for measuring the force applied to said handle.

23. (Previously presented) The system of claim 21, wherein slotted plate further comprises an electrostatic dissipative material disposed to contact said glass panel.

24. (Previously presented) The system of claim 23, wherein said electrostatic dissipative material is a polyacetal plastic alloy.

25. (Previously presented) The system of claim 18, further comprising a vacuum configured to hold the glass panel tightly against said layer of electrostatic dissipative material.

26. (Previously presented) The system of claim 21, wherein the force applied to said handle is applied in a downward direction.

27. (Previously presented) A system for separating edge portions from a glass panel etched with semiconductor circuitry, the glass panel being scored to define an inner working area and outer edge portions to be removed, the system comprising:

a stage having a plurality of channels formed therethrough and a layer of electrostatic dissipative material that covers an upper surface of said stage, wherein gas is pumped through said channels along the underside of the glass panel such that the glass panel floats above said layer of electrostatic dissipative material;

locating pins that are removably secured to said stage, wherein said locating pins locate the glass panel above said stage, the gas no longer being pumped through said channels after the glass panel is located above said stage so that the glass panel directly contacts said layer of electrostatic dissipative material, and wherein at least one of the outer edge portions is located

outside a periphery of said stage when the glass panel directly contacts said layer of electrostatic dissipative material;

a turntable supporting said stage, said turntable configured to mechanically rotate said stage;

a separating device for separating the outer edge portions from the glass panel, said separating device comprising a handle and a slotted plate connected to said handle, said slotted plate having upper and lower panel engaging surfaces defining a recess of approximately the same width and thickness as the glass panel; and

a force gauge attached to said handle for measuring the force applied to said handle.

28. (Previously presented) The system of claim 26, further comprising a vacuum configured to hold the glass panel tightly against said layer of electrostatic dissipative material.